

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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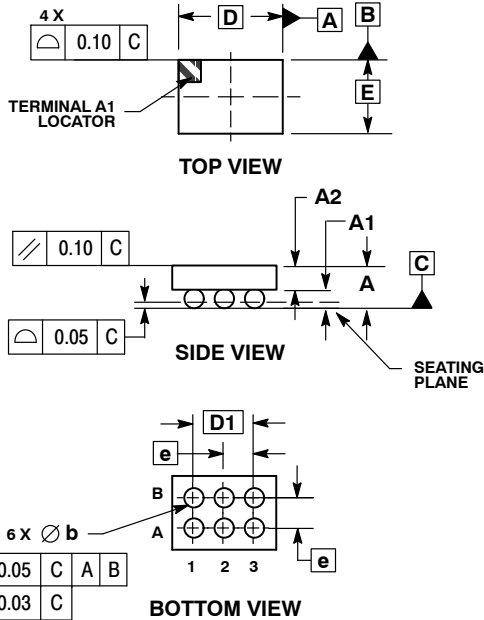


A1

SCALE 4:1

**6 PIN FLIP-CHIP**  
**1.72x1.22mm, 0.5 PITCH**  
**CASE 499J-01**  
**ISSUE O**

DATE 05 FEB 2004



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	1.720 BSC	
E	1.220 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.000 BSC	

**GENERIC MARKING DIAGRAM\***



- xx = Specific Device Code
- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking.

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<b>DESCRIPTION:</b>	<b>6 PIN FLIP-CHIP, 1.72x1.22mm, 0.5 PITCH</b>	<b>PAGE 1 OF 1</b>

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